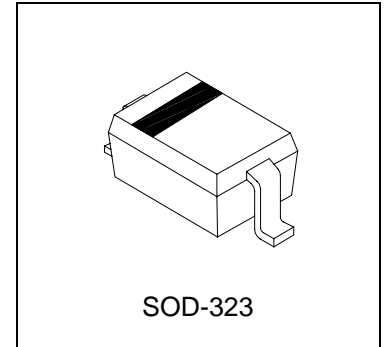




**HMSZ5223B**  
 thru  
**HMSZ5257B** ZENER DIODES



**Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Total Device Dissipation FR-5 Board TA=25°C, Derate above 25°C	PD	225 1.8	mW mW/°C
Total Device Dissipation Alumina Substrate**TA=25°C, Derate above 25°C	PD	300 2.4	mW mW/°C
Thermal Resistance Junction to Ambient	RθJA	417	°C/W
Junction and Storage Temperature	Tj, Tstg	-55 to +150	°C

\*FR-5 - 1.0×0.75×0.062 in. \*\*Alumina - 0.4×0.3×0.024 in. 99.5% alumina.

**Electrical Characteristic** (VF=0.9V Max @IF=10mA for all types.)

Device	Marking Code	Test Current IZT(mA)	Zener Voltage VZ(V)	ZZK IZ=0.25mA ΩMax	ZZT IZ=IZT ΩMax	Max. Reverse Current IR(μA) @VR(V)	
HMSZ5223B	23	20	2.7 ±5%	1300	30	75	1.0
HMSZ5226B	26	20	3.3 ±5%	1600	28	25	1.0
HMSZ5227B	27	20	3.6 ±5%	1700	24	15	1.0
HMSZ5228B	28	20	3.9 ±5%	1900	23	10	1.0
HMSZ5229B	29	20	4.3 ±5%	2000	22	5.0	1.0
HMSZ5230B	30	20	4.7 ±5%	1900	19	5.0	2.0
HMSZ5231B	31	20	5.1 ±5%	1600	17	5.0	2.0
HMSZ5232B	32	20	5.6 ±5%	1600	11	5.0	3.0
HMSZ5233B	33	20	6.0 ±5%	1600	7.0	5.0	3.5
HMSZ5234B	34	20	6.2 ±5%	1000	7.0	5.0	4.0
HMSZ5235B	25	20	6.8 ±5%	750	5.0	3.0	5.0
HMSZ5236B	36	20	7.5 ±5%	500	6.0	3.0	6.0
HMSZ5237B	37	20	8.2 ±5%	500	8.0	3.0	6.5
HMSZ5238B	38	20	8.7 ±5%	600	8.0	3.0	6.5
HMSZ5239B	39	20	9.1 ±5%	600	10	3.0	7.0
HMSZ5240B	40	20	10 ±5%	600	17	3.0	8.0
HMSZ5241B	41	20	11 ±5%	600	22	2.0	8.4
HMSZ5242B	42	20	12 ±5%	600	30	1.0	9.1
HMSZ5243B	43	9.5	13 ±5%	600	13	0.5	9.9



# HI-SINCERITY

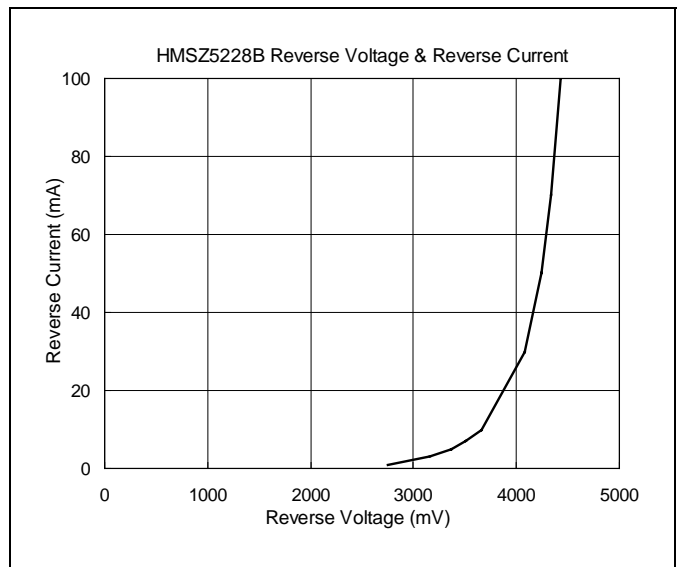
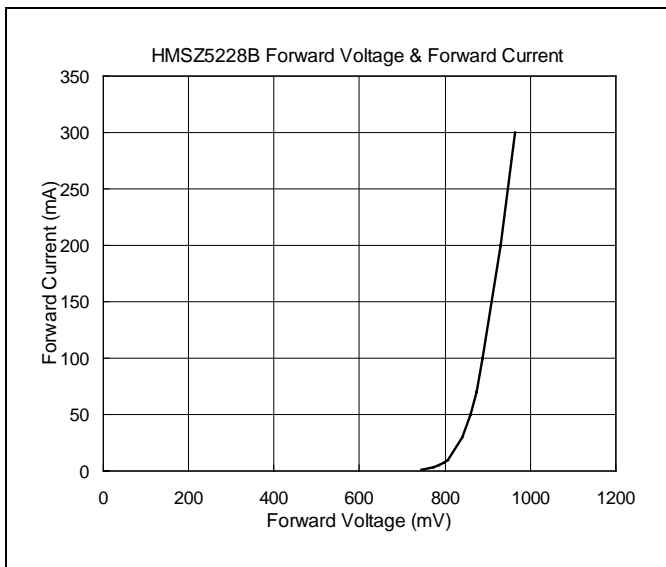
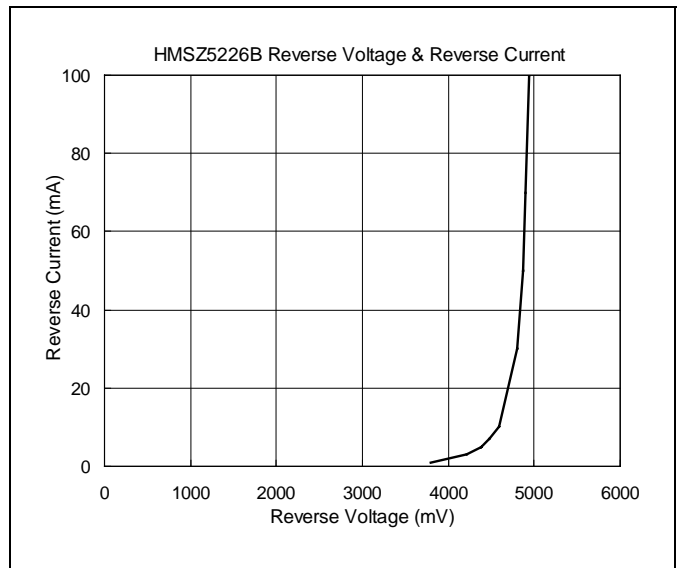
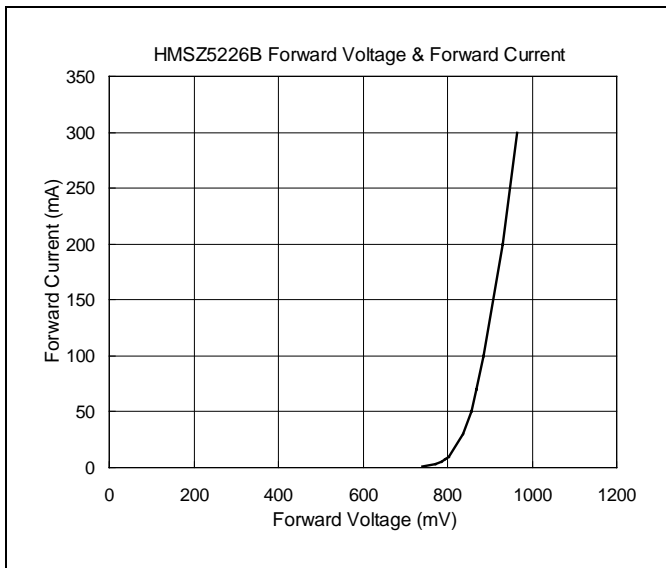
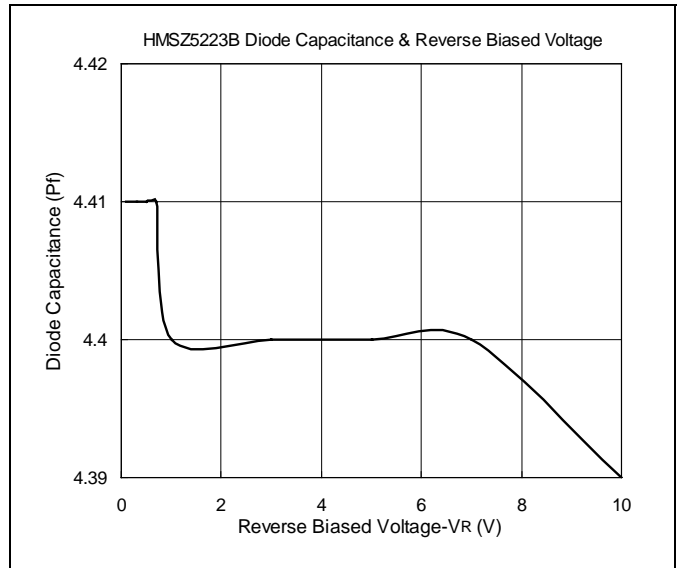
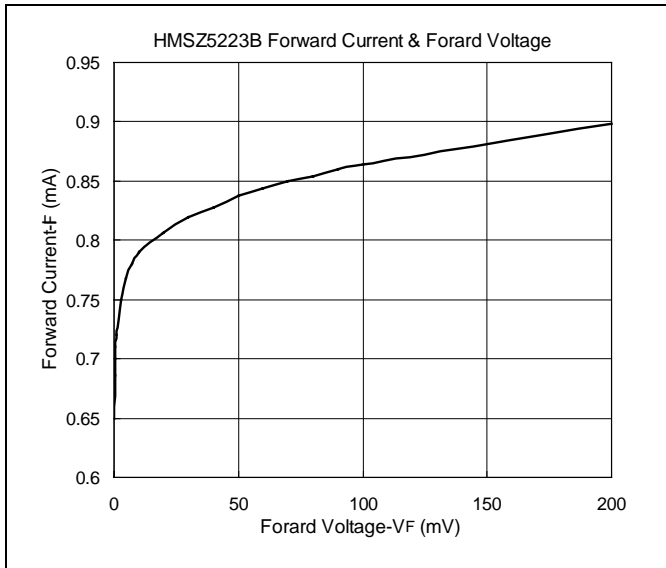
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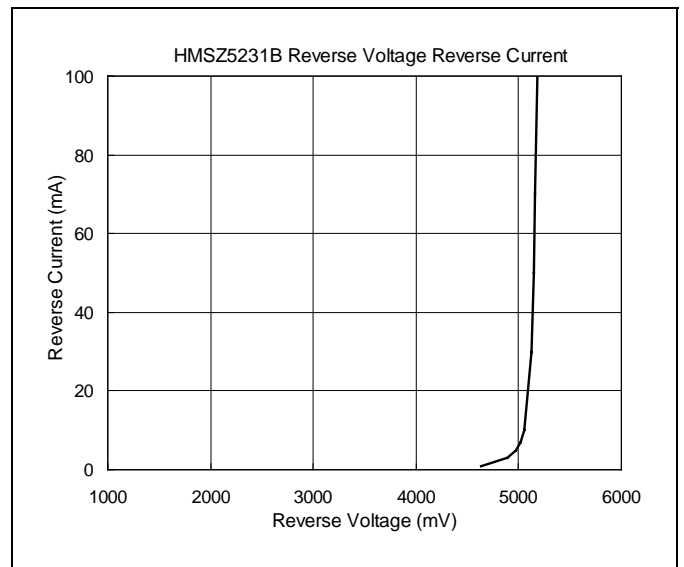
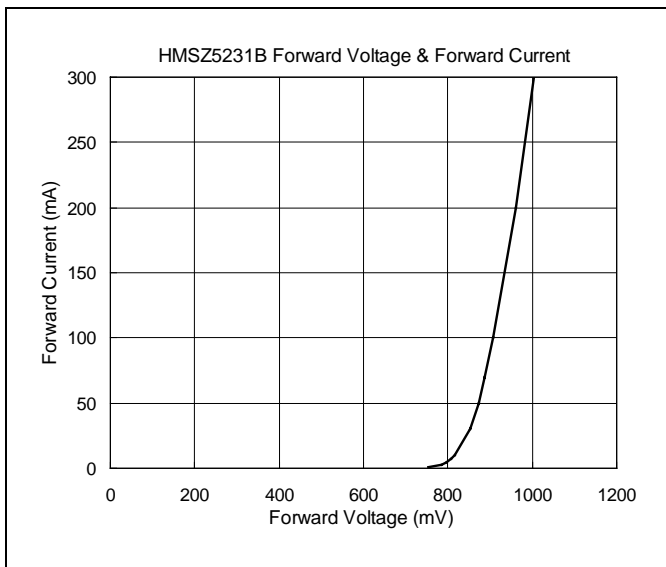
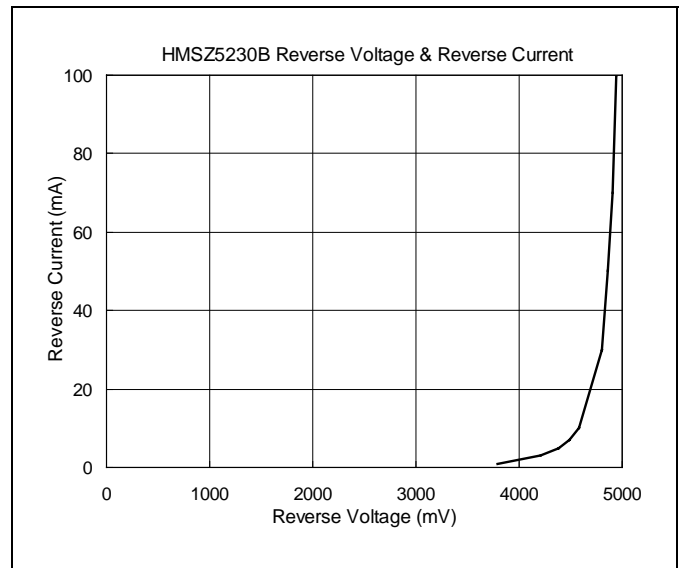
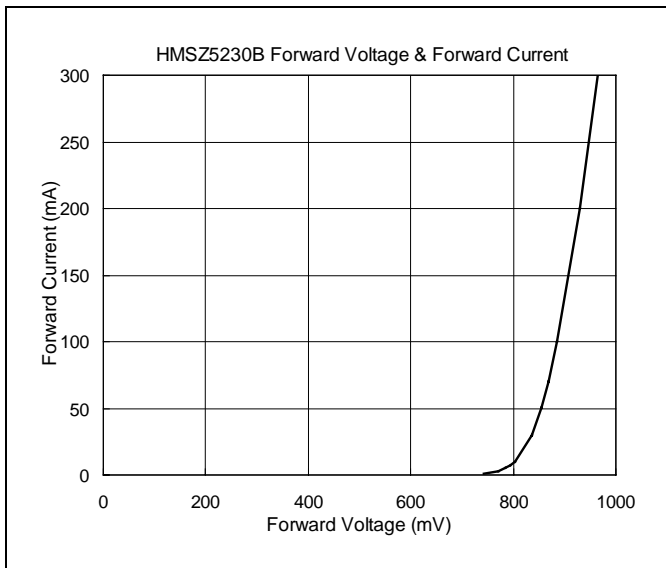
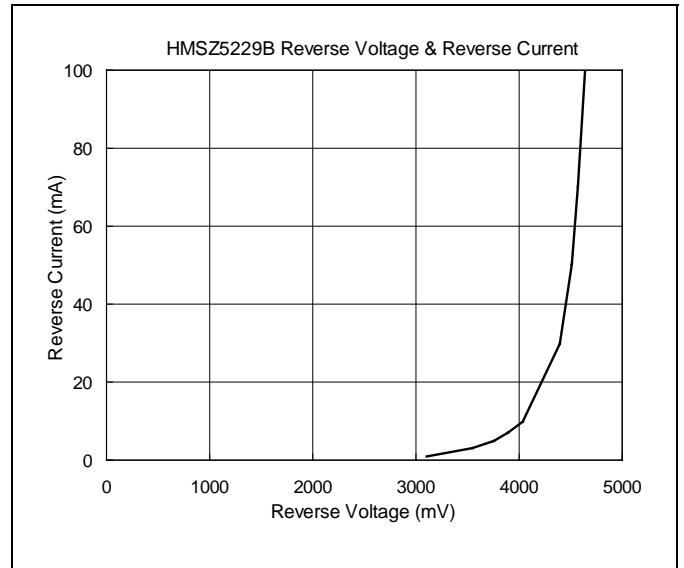
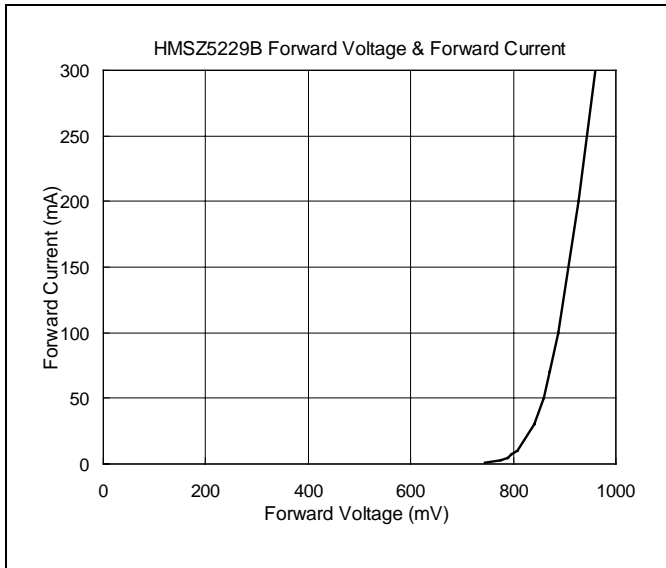
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Issued Date : 2001.11.01  
Revised Date : 2001.11.22  
Page No. : 2/12

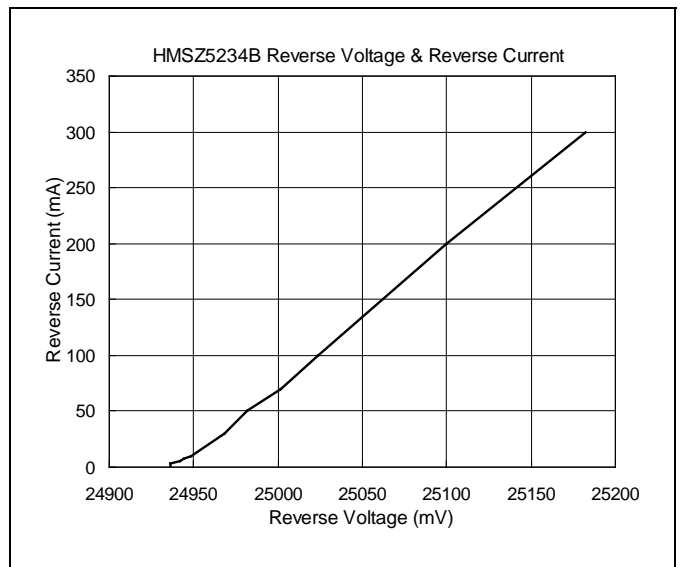
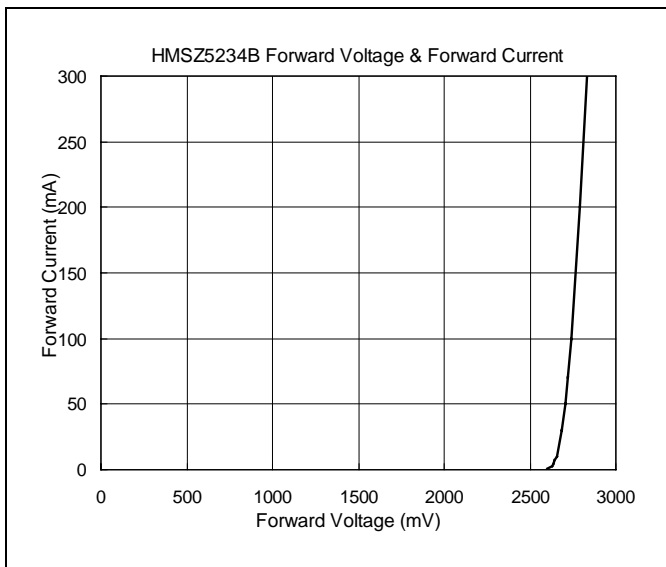
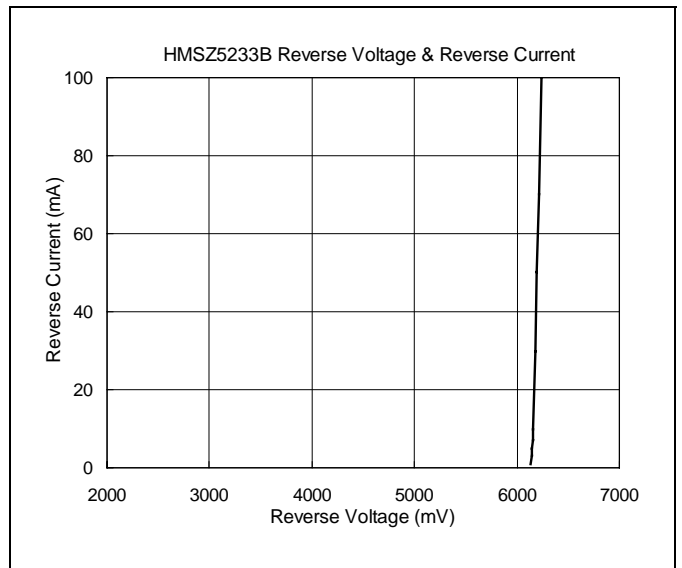
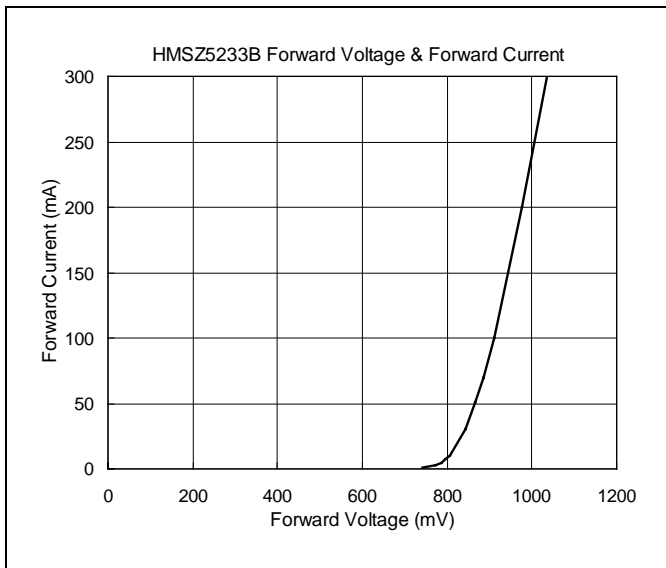
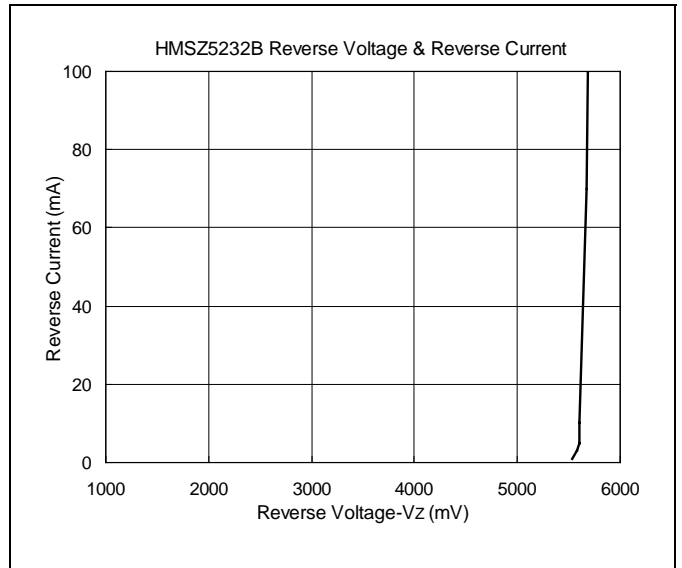
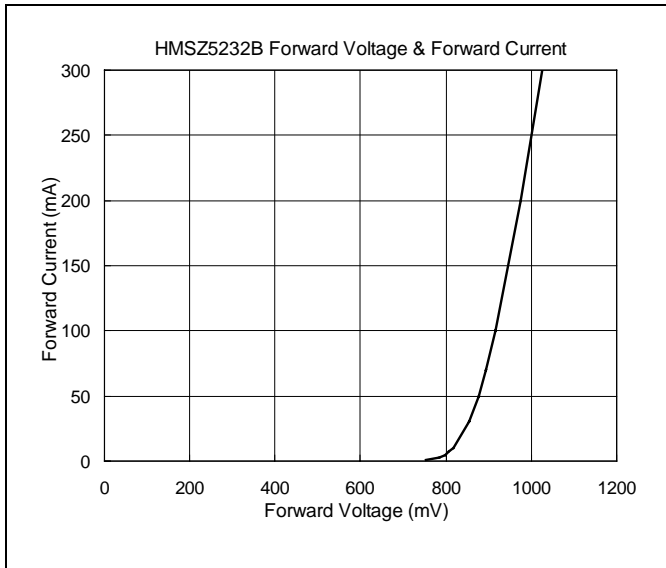
Device	Marking Code	Test Current IZT(mA)	Zener Voltage VZ(V)	ZZK IZ=0.25mA ΩMax	ZZT IZ=IZT ΩMax	Max. Reverse Current	
						IR(μA)	@VR(V)
HMSZ5244B	44	9.0	14 ±5%	600	15	0.1	10
HMSZ5245B	45	8.5	15 ±5%	600	16	0.1	11
HMSZ5246B	46	7.8	16 ±5%	600	17	0.1	12
HMSZ5247B	47	7.4	17 ±5%	600	19	0.1	13
HMSZ5248B	48	7.0	18 ±5%	600	21	0.1	14
HMSZ5249B	49	6.6	19 ±5%	600	23	0.1	14
HMSZ5250B	50	6.2	20 ±5%	600	25	0.1	15
HMSZ5251B	51	5.6	22 ±5%	600	29	0.1	17
HMSZ5252B	52	5.2	24 ±5%	600	33	0.1	18
HMSZ5253B	53	5.0	25 ±5%	600	35	0.1	19
HMSZ5254B	54	4.6	27 ±5%	600	41	0.1	21
HMSZ5255B	55	4.5	28 ±5%	600	44	0.1	21
HMSZ5256B	56	4.2	30 ±5%	600	49	0.1	23
HMSZ5257B	57	3.8	33 ±5%	700	58	0.1	25

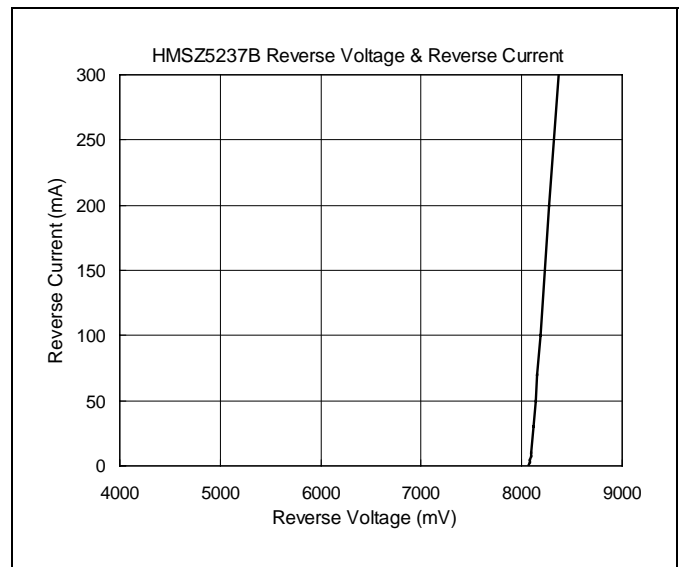
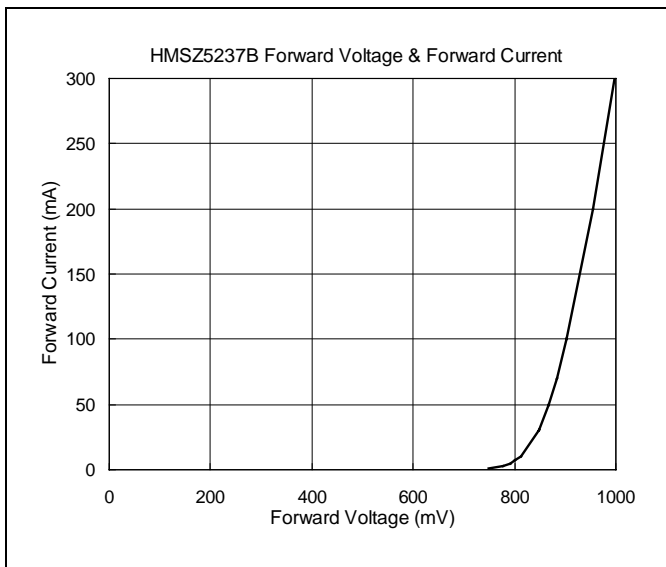
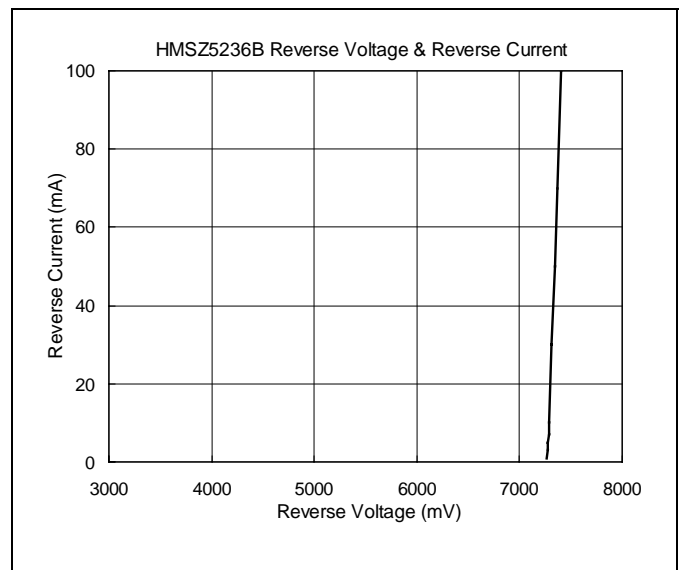
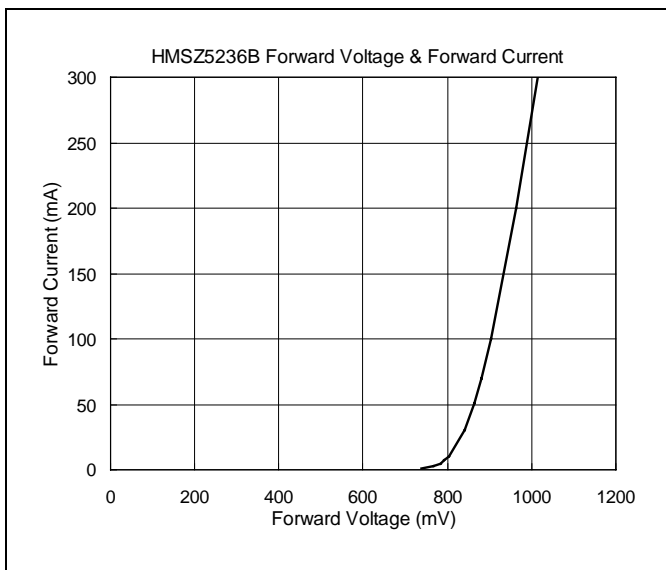
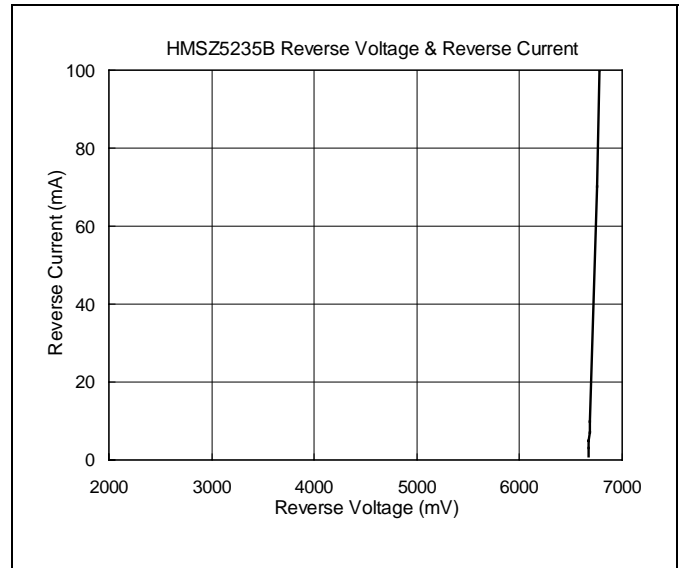
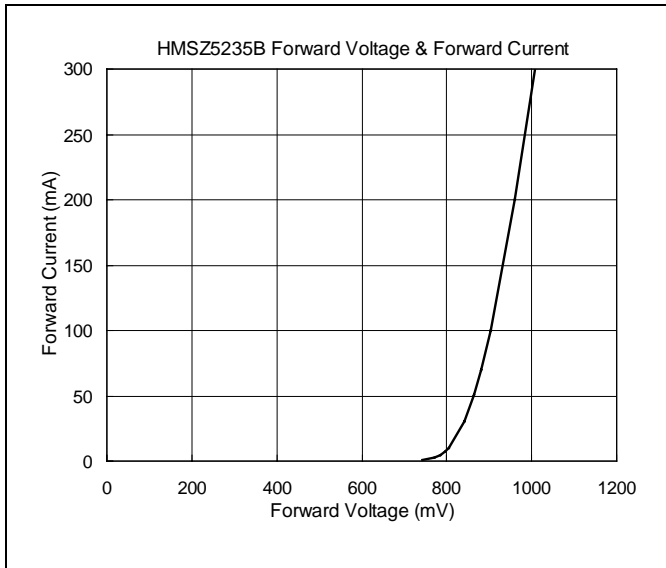


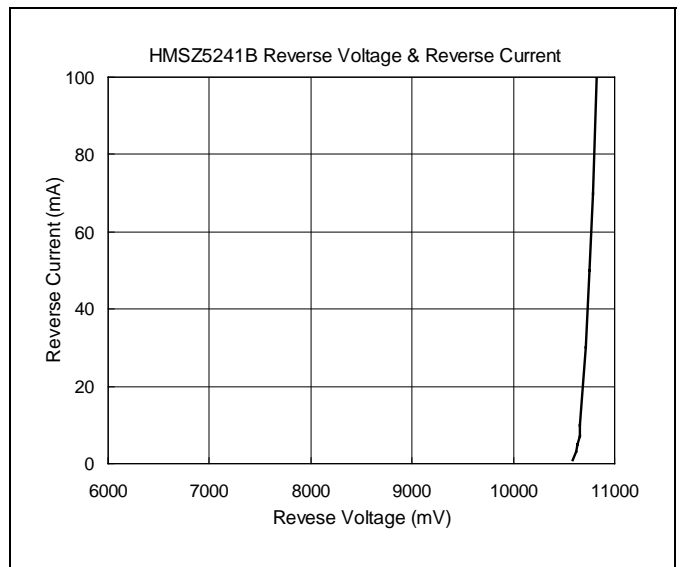
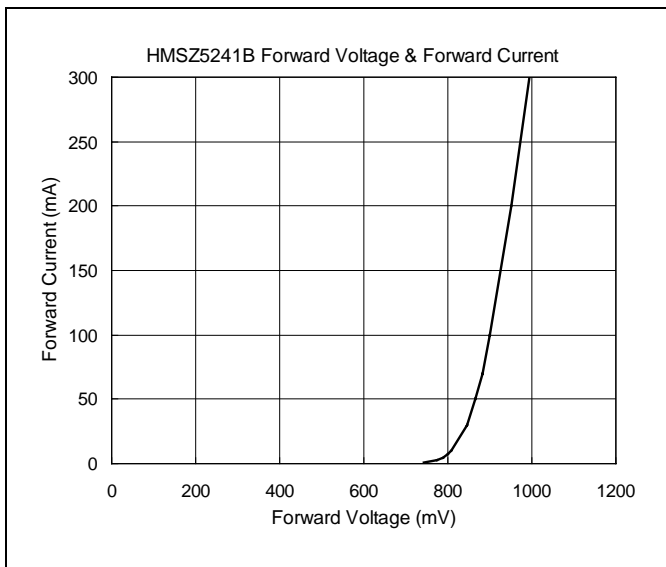
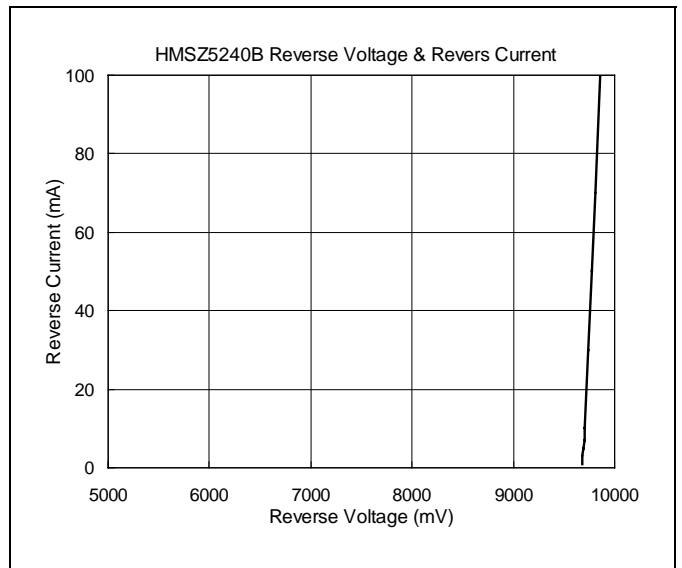
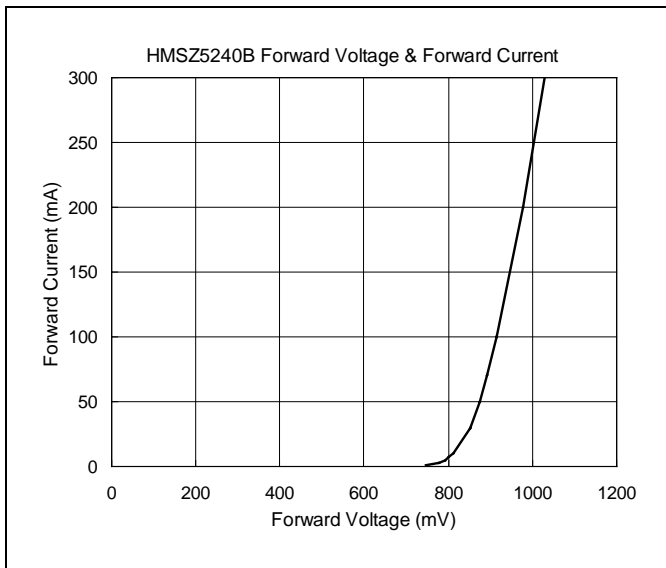
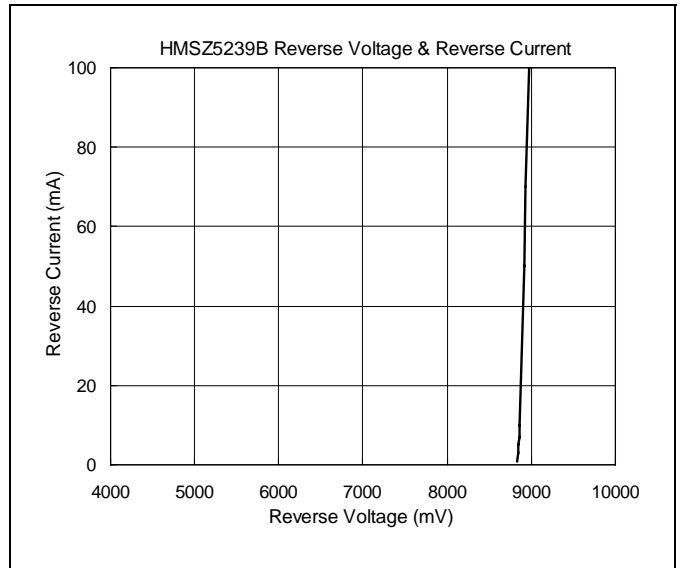
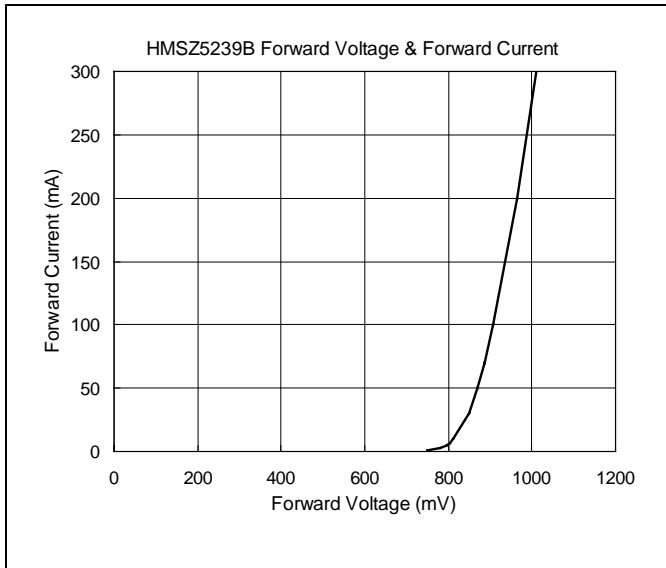
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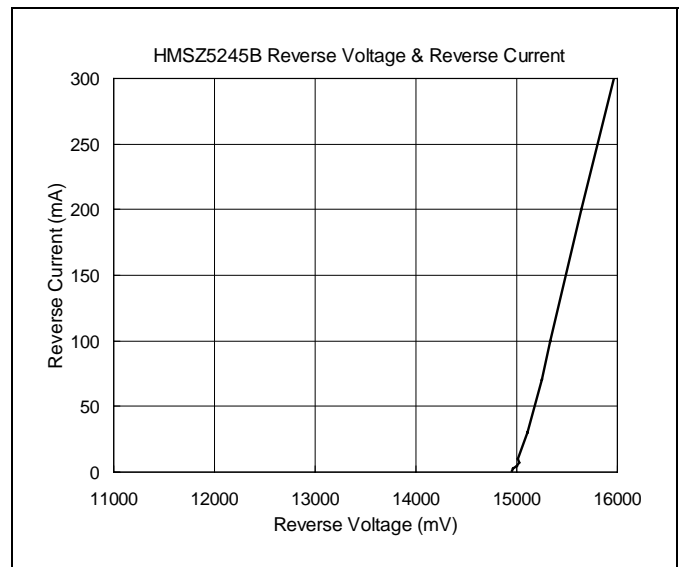
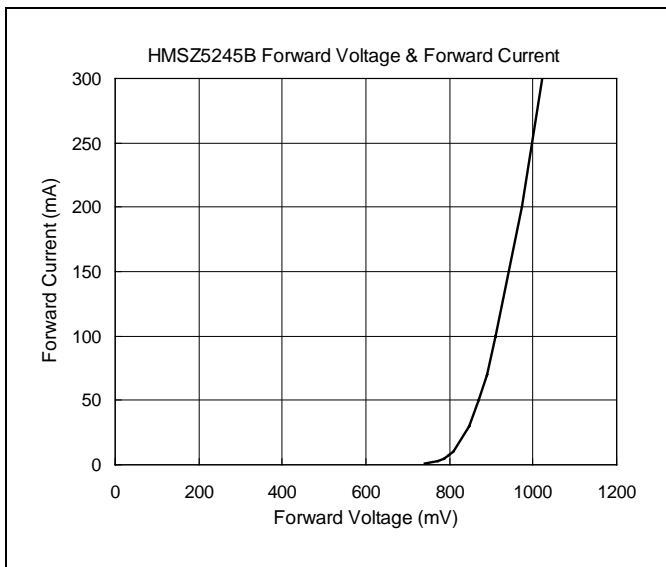
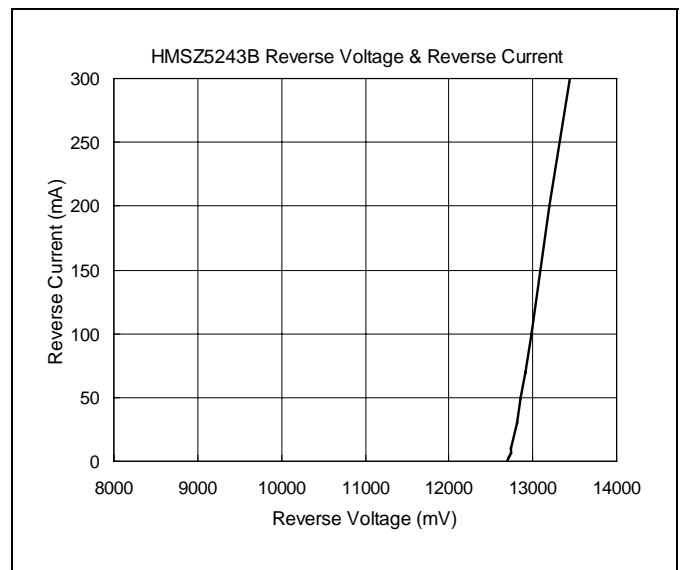
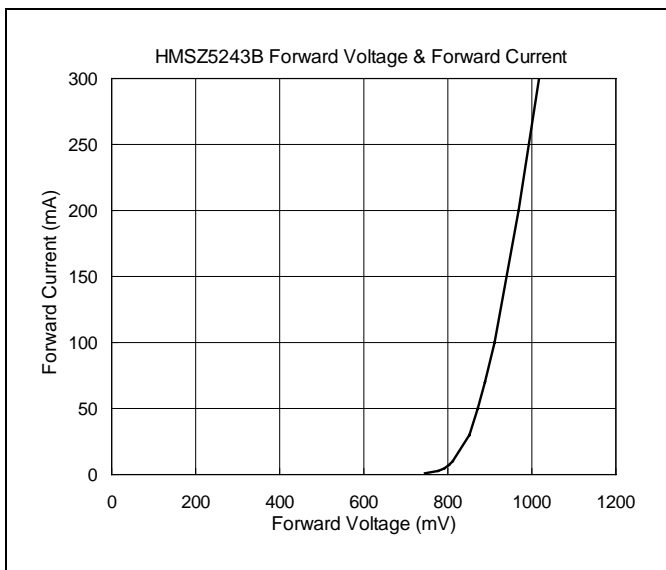
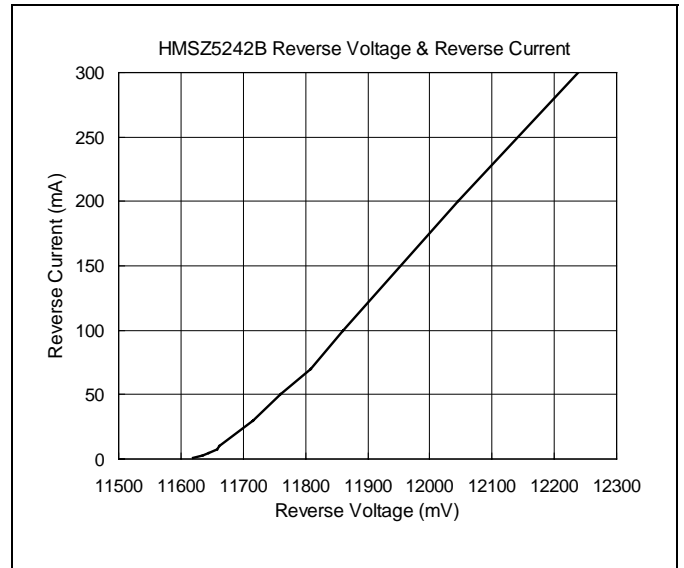
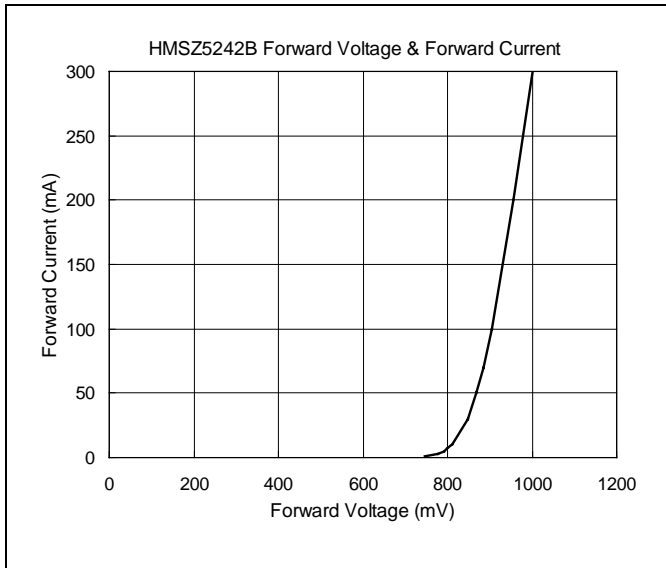




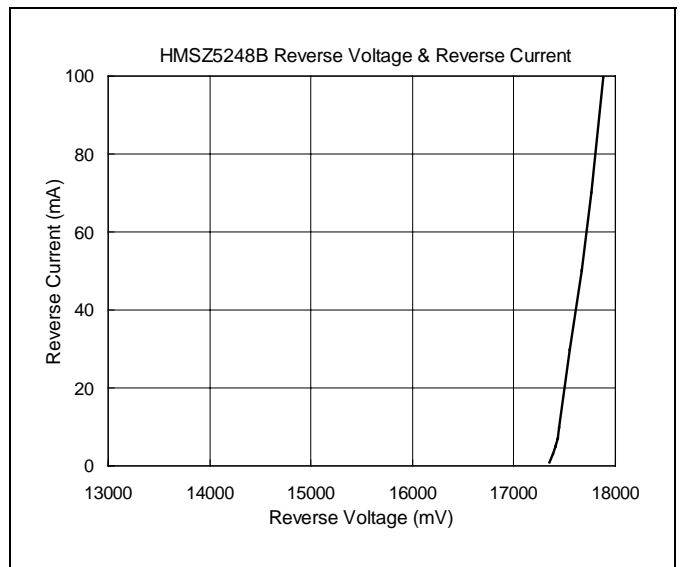
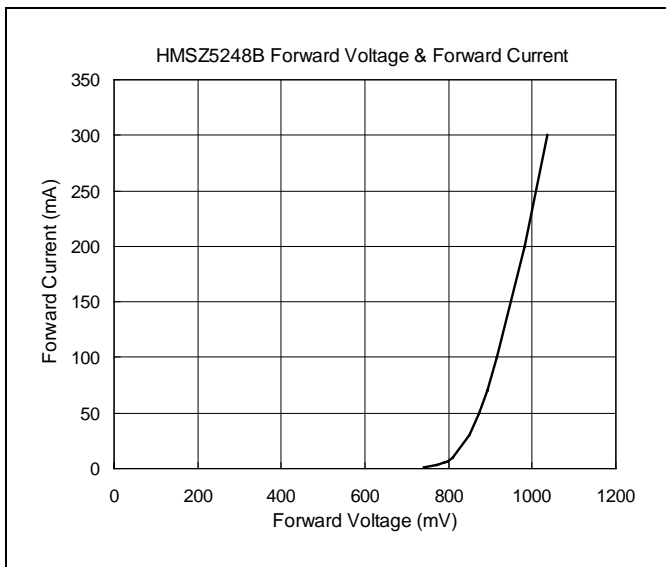
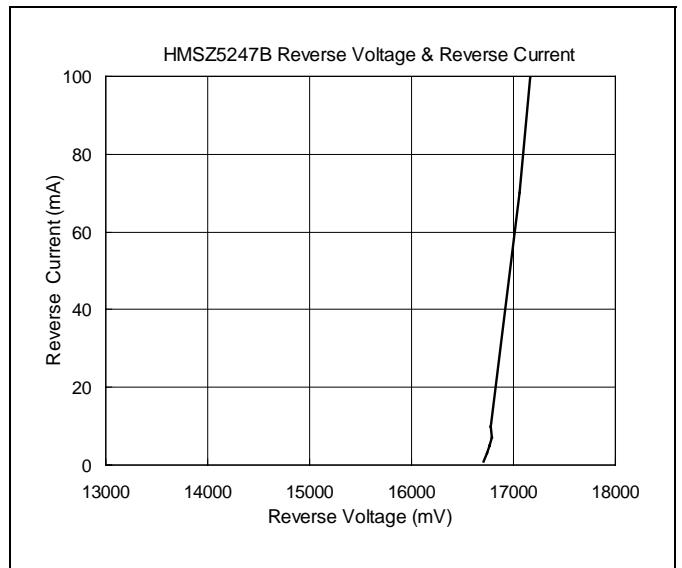
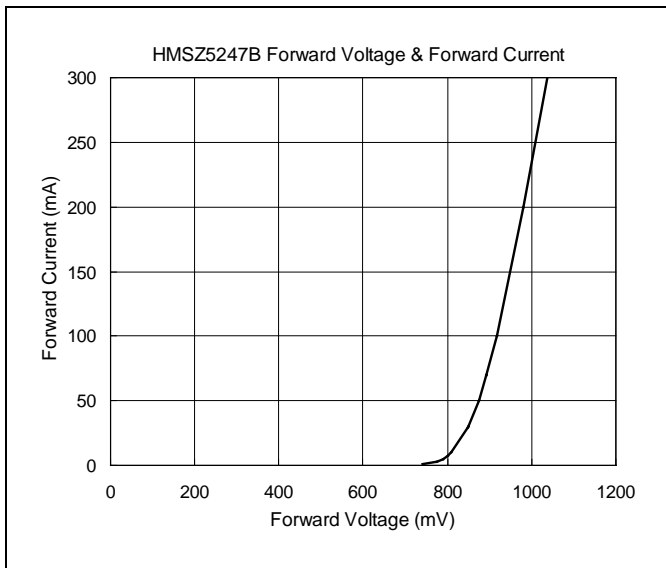
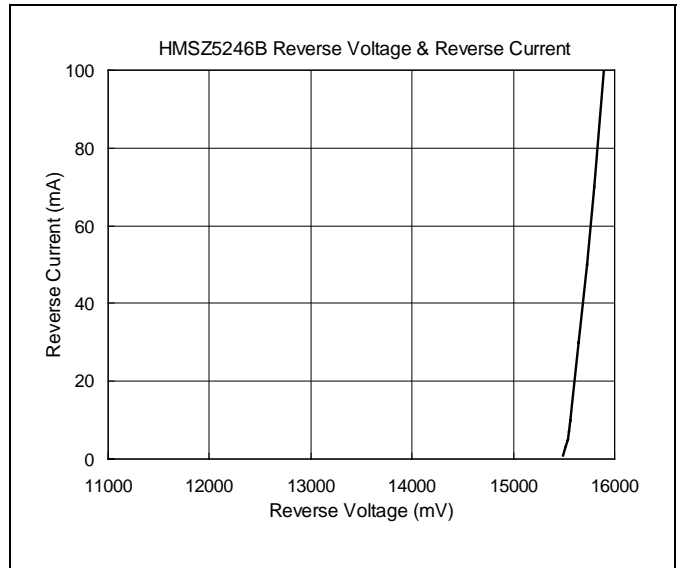
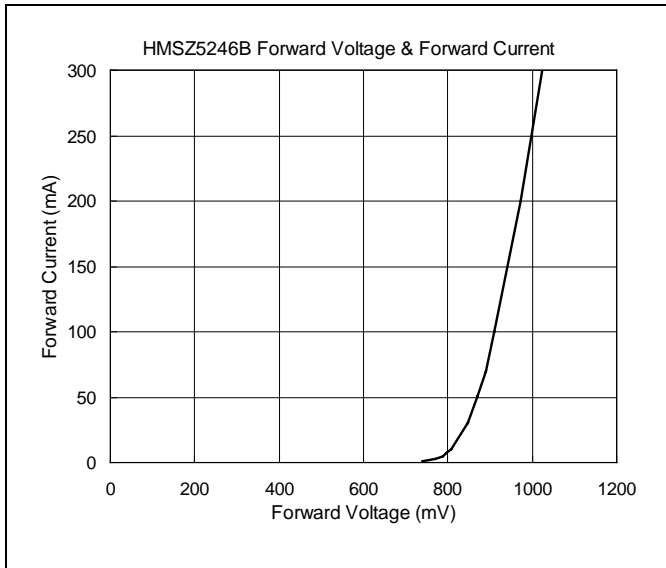


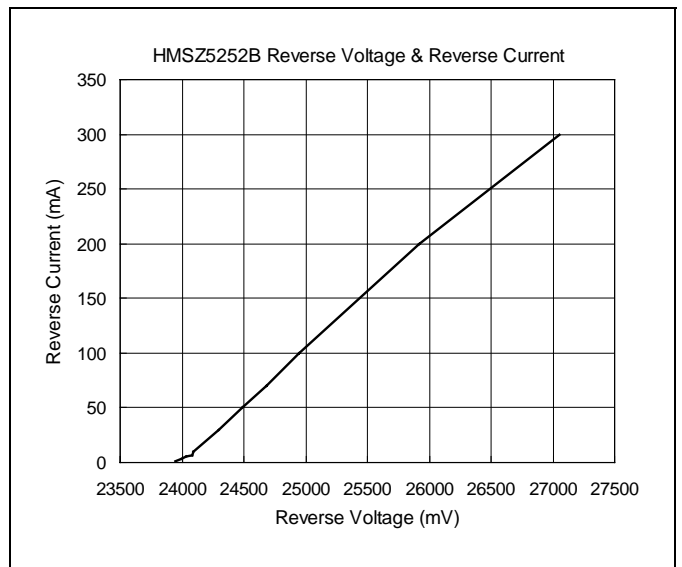
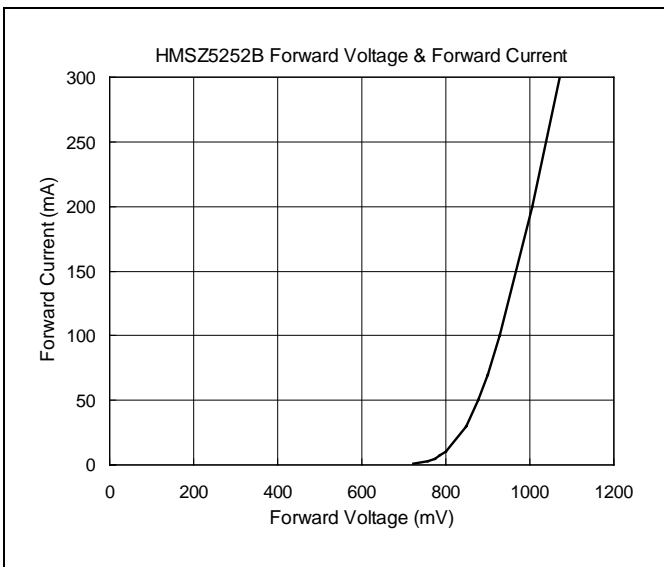
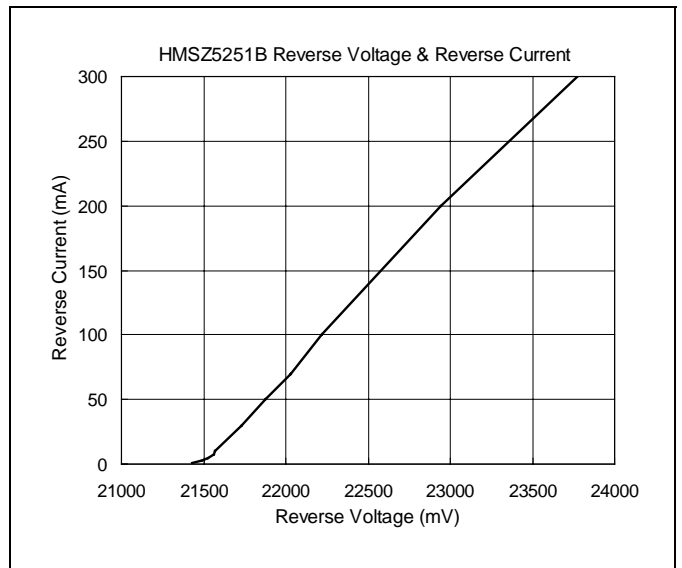
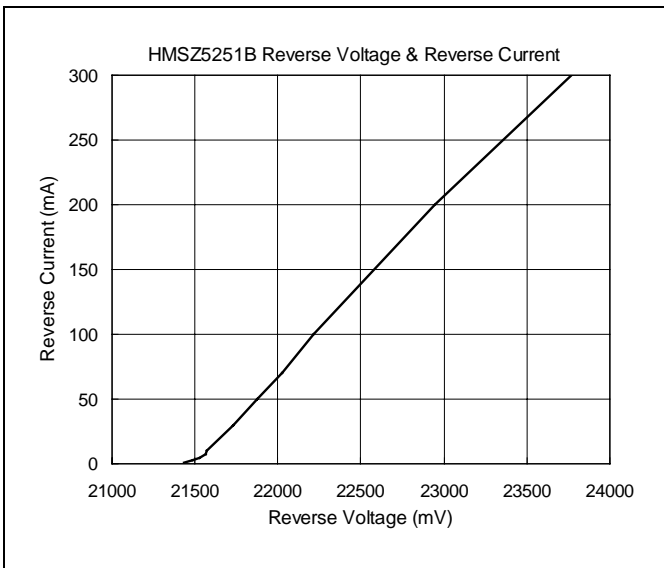
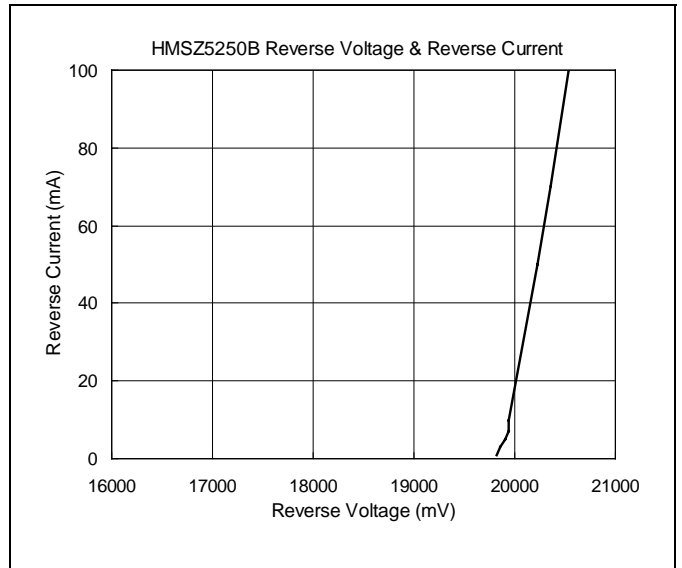
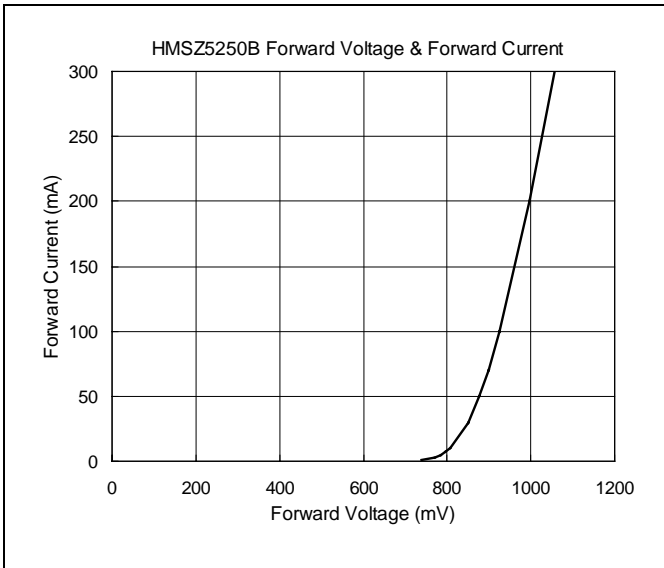


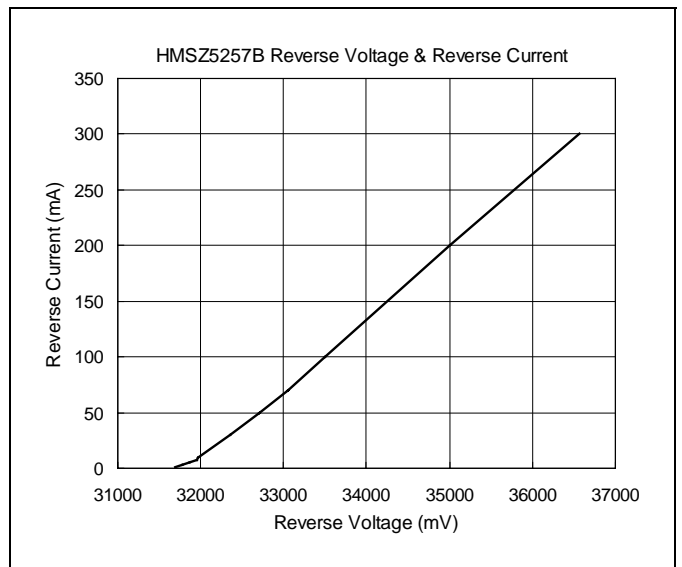
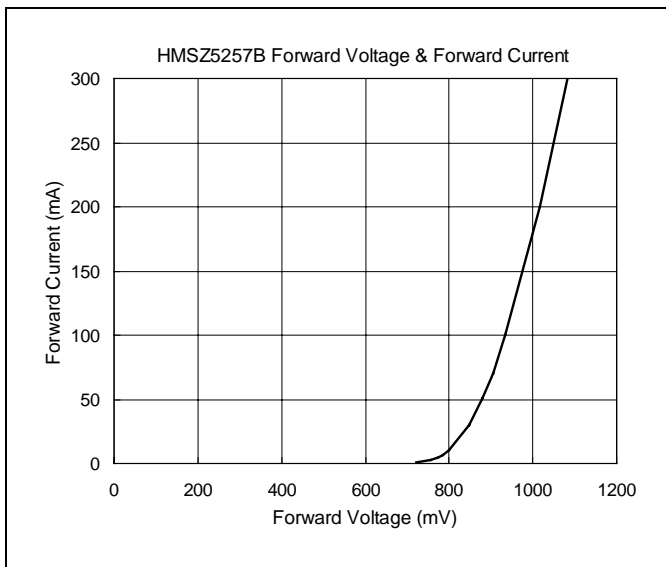
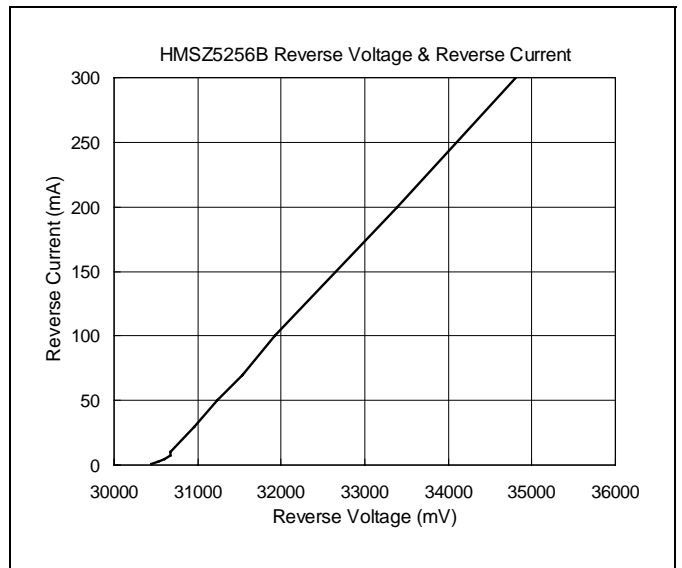
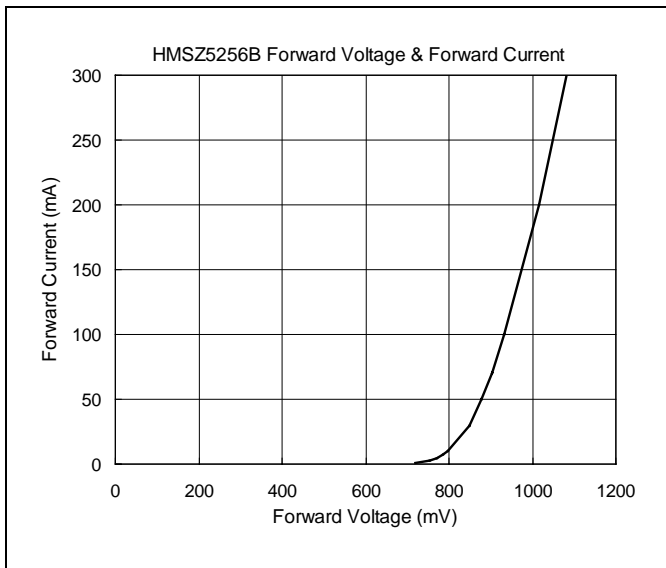
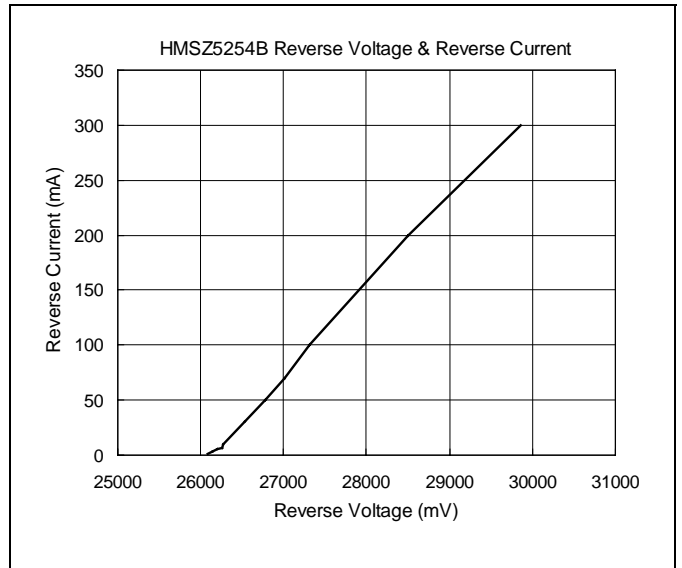
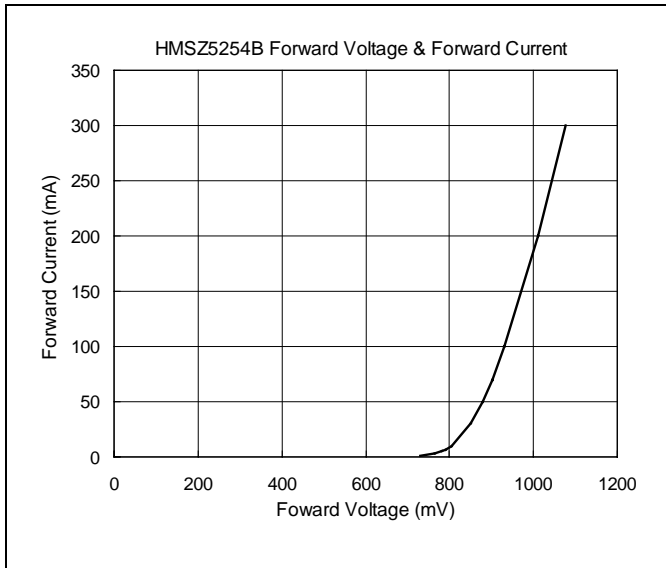






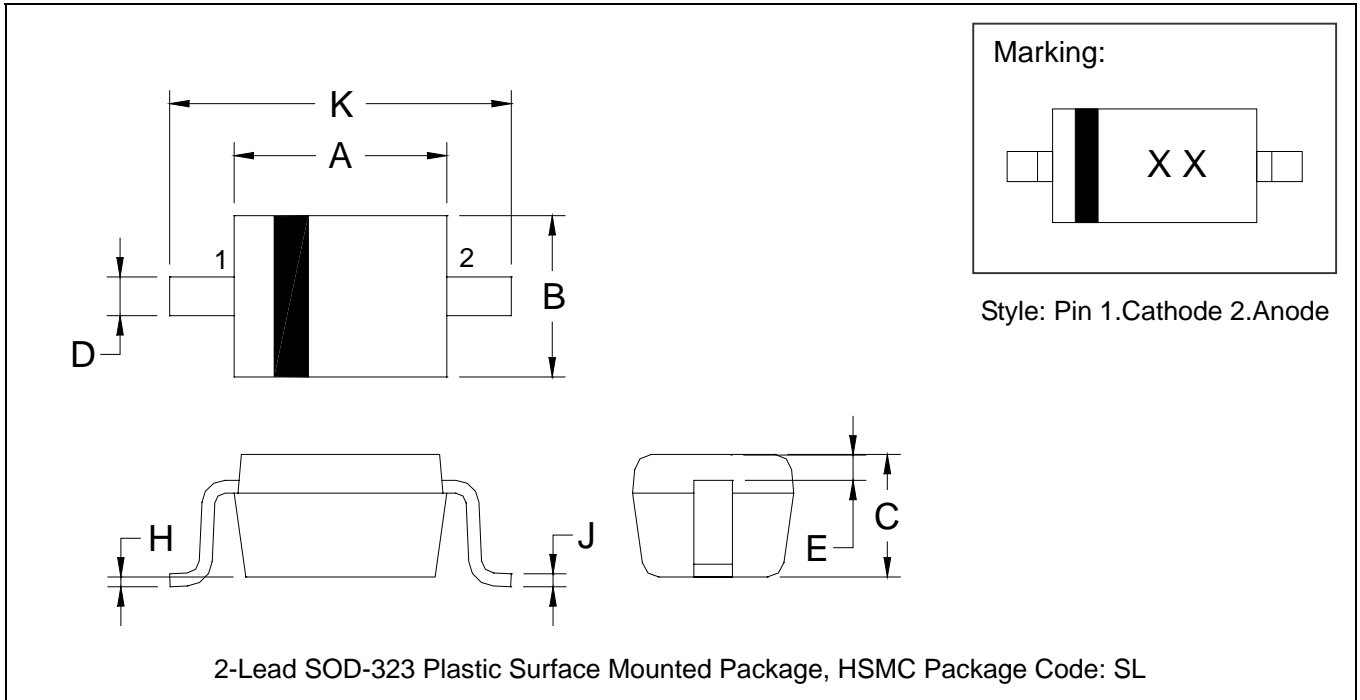








### SOD-323 Dimension



\*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.0630	0.0709	1.60	1.80	E	0.0060	-	0.15	-
B	0.0453	0.0531	1.15	1.35	H	0.0000	0.0040	0.00	0.10
C	0.0315	0.0394	0.80	1.00	J	0.0035	0.0070	0.089	0.177
D	0.0098	0.0157	0.25	0.40	K	0.0906	0.1063	2.30	2.70

- Notes: 1.Dimension and tolerance based on our Spec. dated DEC. 20, 2000.  
 2.Controlling dimension : millimeters.  
 3.Lead thickness specified per L/F drawing with solder plating.  
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

**Material:**

- Lead: 42 Alloy ; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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